



Material Content Data Sheet



Sales Product Name		BTN8962TA		Issued		25. September 2017		
MA#		MA001079226						
Package		PG-TO263-7-1		Weight*		1533.38 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	6.071	0.40	0.40	3959	3959
leadframe	non noble metal	iron	7439-89-6	0.810	0.05		528	
	inorganic material	phosphorus	7723-14-0	0.243	0.02		158	
	non noble metal	copper	7440-50-8	808.613	52.73	52.80	527342	528028
wire	non noble metal	aluminium	7429-90-5	6.626	0.43	0.43	4321	4321
encapsulation	organic material	carbon black	1333-86-4	8.801	0.57		5740	
	plastics	epoxy resin	-	96.814	6.31		63138	
	inorganic material	silicondioxide	60676-86-0	481.136	31.38	38.26	313775	382653
leadfinish	non noble metal	tin	7440-31-5	13.037	0.85	0.85	8502	8502
plating	non noble metal	nickel	7440-02-0	0.212	0.01		139	
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.01	527341	139
glue	plastics	Polyimide	26023-21-2	0.179	0.01	0.01	117	117
solder	noble metal	silver	7440-22-4	0.112	0.01		73	
	non noble metal	tin	7440-31-5	0.090	0.01		59	
	non noble metal	lead	7439-92-1	4.284	0.28	0.30	2794	2926
heatspreader	non noble metal	iron	7439-89-6	0.106	0.01		69	
	inorganic material	phosphorus	7723-14-0	0.032	0.00		21	
	non noble metal	copper	7440-50-8	106.210	6.93	6.94	69265	69355
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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